+357 96 030922
info@marketpublishers.com

Global HBM2 DRAM Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

https://marketpublishers.com/r/G742371CCC7FEN.html
Date: June 2026
Pages: 83
Price: US$ 3,480.00 (Single User License)
ID: G742371CCC7FEN

Abstracts

According to our (Global Info Research) latest study, the global HBM2 DRAM market size was valued at US$ 154 million in 2025 and is forecast to a readjusted size of US$ 44.23 million by 2032 with a CAGR of -16.2% during review period.

HBM2 memory is the second generation of high bandwidth stacked DRAM designed for artificial intelligence training, high performance computing, graphics processing, and other high throughput data systems. Its core purpose is to provide far more bandwidth between processors and memory than conventional DDR and GDDR approaches while reducing system bottlenecks through a smaller footprint and better energy efficiency. Based on the official materials from Samsung, SK hynix, and Micron, these products generally use through silicon vias to vertically stack multiple DRAM layers and are tightly integrated in the same package with GPUs, CPUs, TPUs, or other ASICs, thereby shortening signal paths, increasing parallel data throughput, and improving power and thermal behavior. As HBM2 evolved into HBM2E, per stack capacity, per pin speed, and bandwidth all increased, with representative products spanning 8GB and 16GB capacities and performance levels such as 307 GB/s, 410 GB/s, and 460 GB/s per stack. The main customers are GPU vendors, AI accelerator suppliers, server and supercomputing system makers, and advanced packaging partners that need high bandwidth memory subsystems. The usual delivery format is not a standard memory module but rather known good stacked die or highly integrated stacked devices supplied by the memory manufacturer and then combined with the host chip in a system package by OSATs or system companies. As a result, the business model is closer to high end customized component supply and long cycle design in. In industry terms, HBM2 and HBM2E are fundamentally critical memory layers within AI infrastructure and advanced computing platforms, serving large model training, scientific computing, complex graphics rendering, network switching, and selected high end automotive

+357 96 030922
info@marketpublishers.com

electronics scenarios that must move massive amounts of data within a constrained area.

From a product and technology perspective, HBM2 and HBM2E are not simply upgraded general purpose DRAM. They are specialized high bandwidth solutions designed to restructure the relationship between memory and processors for highly parallel computing workloads. Samsung describes HBM as using TSV stacking, a wide interface, and high throughput architecture to serve AI training and high performance computing. SK hynix presents HBM2E as a system level solution defined by high speed, wide I/O, and improved thermal efficiency. Micron further states that HBM2E is intended for applications demanding maximum throughput between memory and processing and can serve as an alternative to selected GDDR6 and GDDR6X use cases. This indicates that the HBM2 family is not tied to any single graphics generation but to the broader system bottlenecks created by AI training, scientific computing, graphics rendering, and high throughput data processing. Samsung HBM2 Aquabolt reached 8GB, 2.4Gbps per pin, and 307 GB/s, Samsung HBM2E Flashbolt raised per stack capacity to 16GB and bandwidth to 410 GB/s, SK hynix HBM2E reached 3.6Gbps and 460 GB/s, and Micron documentation lists 8GB and 16GB devices with 1,024 bit I/O and up to 410 GB/s. As model sizes expand, compute cluster density rises, and accelerator platforms demand more memory bandwidth, the gains in capacity, bandwidth, efficiency, and packaging synergy from HBM2 to HBM2E have become a major performance lever for modern computing platforms.

From an industry organization perspective, the competitive logic of HBM2 and HBM2E is clearly different from that of standard memory products. Micron’s technical materials show that HBM2E is typically shipped as known good stacked die and must be integrated by OSATs or system companies with CPUs, GPUs, TPUs, and other host chips at the system package level. A typical system may contain four to six HBM2E devices. This means competition no longer depends only on wafer manufacturing and bit cost, but increasingly on TSV process capability, stacking yield, thermal management, interconnect design, and coordination with advanced packaging partners. Samsung repeatedly emphasizes optimization in TSV design, thermal control, stack structure, and stable data transmission across its HBM2 and HBM2E materials, while SK hynix presents bandwidth, thermal improvement, and its next generation HBM roadmap together, showing that leading companies have shifted from single device competition to joint optimization across device, packaging, and system layers. Because HBM products must be co developed with accelerator chips, silicon interposers, package substrates, and system design, customer qualification cycles are longer, validation thresholds are higher, and supplier relationships become more long term.

+357 96 030922
info@marketpublishers.com

Combined with U.S. CHIPS support for Micron’s DRAM manufacturing and SK hynix’s Indiana advanced packaging and R and D plan, future HBM expansion will not be just about more output, but also about localized manufacturing, advanced packaging, and AI supply chain restructuring, keeping entry barriers high.

From a regional and commercial perspective, the HBM2 family has relatively few manufacturers but very strong global reach, showing a pattern of highly concentrated upstream supply and broadly distributed downstream demand. At present, the original manufacturers that can be clearly verified through official product pages are concentrated in Korea and the United States. Korea has Samsung Electronics and SK hynix as two core suppliers, while the United States has Micron as its representative producer, resulting in a highly concentrated supply side. At the same time, Samsung Semiconductor has already built a global network covering China, Southeast Asia, Europe, the Middle East, Africa, and the Americas. Micron has operations and support footprints across the Americas and Asia Pacific, and SK hynix maintains overseas network nodes including the United States beyond its Korean headquarters. This indicates that HBM2 and HBM2E consumption is not confined to a single region but spreads globally alongside AI servers, supercomputing centers, graphics systems, networking equipment, and other high end electronic systems. For industry prospects, this combination of concentrated supply and outward spreading demand usually means rising pricing power and strategic importance for high end memory, while also making it easier for leading suppliers to lock in key customers through global sales networks and local support structures. Even as HBM2 is succeeded by newer generations, it should retain clear value in installed platforms, cost sensitive high bandwidth scenarios, and technology migration across the supply chain, and continue to generate stable high value revenue opportunities for leading vendors.

This report is a detailed and comprehensive analysis for global HBM2 DRAM market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global HBM2 DRAM market size and forecasts, in consumption value ($ Million), sales quantity (Million Units), and average selling prices (US$/Unit), 2021-2032

+357 96 030922
info@marketpublishers.com

Global HBM2 DRAM market size and forecasts by region and country, in consumption value ($ Million), sales quantity (Million Units), and average selling prices (US$/Unit), 2021-2032

Global HBM2 DRAM market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (Million Units), and average selling prices (US$/Unit), 2021-2032

Global HBM2 DRAM market shares of main players, shipments in revenue ($ Million), sales quantity (Million Units), and ASP (US$/Unit), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for HBM2 DRAM

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global HBM2 DRAM market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include SK Hynix, Samsung, Micron, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

HBM2 DRAM market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

+357 96 030922
info@marketpublishers.com

4 G

8 G

16 G

Others

Market segment by Generation Type

HBM2

HBM2E

Market segment by Per-Stack Bandwidth Tier

307GB/s Tier

410GB/s Tier

460GB/s Tier

Market segment by Application

Data Center AI Acceleration Systems

Professional Computing Systems

Industry Embedded Systems

Major players covered

SK Hynix

Samsung

+357 96 030922
info@marketpublishers.com

Micron

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe HBM2 DRAM product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of HBM2 DRAM, with price, sales quantity, revenue, and global market share of HBM2 DRAM from 2021 to 2026.

Chapter 3, the HBM2 DRAM competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the HBM2 DRAM breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026.and HBM2 DRAM market forecast, by regions, by Type, and by Application, with sales and revenue, from 2027 to 2032.

+357 96 030922
info@marketpublishers.com

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of HBM2 DRAM.

Chapter 14 and 15, to describe HBM2 DRAM sales channel, distributors, customers, research findings and conclusion.

+357 96 030922
info@marketpublishers.com

Contents

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

List Of Tables

LIST OF TABLES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

List Of Figures

LIST OF FIGURES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

I would like to order

Product name: Global HBM2 DRAM Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

Product link: https://marketpublishers.com/r/G742371CCC7FEN.html

Price: US$ 3,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:
info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/G742371CCC7FEN.html